

Amendments To the Claims

Claims 1-7 (Previously Cancelled).

Claim 8 (Currently Amended):

A method of manufacturing a thin film negative temperature coefficient thermistor comprising:

~~determining a standardized physical size for the thin film negative temperature coefficient thermistor;~~

~~selecting a negative temperature coefficient of resistance versus temperature curve;~~

selecting a mixture of metal film materials oxides to provide the negative temperature coefficient of resistance versus temperature curve while maintaining ~~the~~ a standardized physical size for the thermistor; and

sputter depositing the mixture of metal film materials oxides on a substrate using a thin film process to form a resistive element.

Claim 9 (Original): The method of claim 8 further comprising:

associating a negative temperature coefficient of resistance versus temperature curve with the thin film negative temperature coefficient thermistor.

Claim 10 (Previously Amended): The method of claim 8 wherein the mixture is a mixture of manganese oxide and nickel oxide.

Claim 11 (Original): The method of manufacturing a thin film negative temperature coefficient thermistor of claim 8 further comprising:

planarizing a substrate prior to the depositing step;  
sputtering conductor terminals;  
sputtering a passivation layer; and  
heat treating.

Claim 12 (Original): The method of claim 11 wherein the step of planarizing is applying silicon nitride film.

Claim 13 (Original): The method of claim 11 wherein the step of sputtering a passivation layer is sputtering silicon nitride film.

Claim 14 (Previously Cancelled).

Claim 15 (Previously Added): The method of claim 8 wherein the step of depositing is sputter depositing.

Claim 16 (Currently Amended): A method of manufacturing a thin film negative temperature coefficient thermistor, comprising:  
~~determining a standardized physical size for the thin film negative temperature coefficient~~  
~~thermistor;~~

selecting a mixture of metal film materials oxides to provide desired negative temperature coefficient of resistance properties ~~while maintaining the standardized physical size and~~

sputter depositing the metal film materials oxides on a substrate to form a resistive element  
using a thin film process.

Claim 17 (Currently Amended): A method of manufacturing a thin film negative temperature coefficient thermistor of a standardized package size, comprising sputter depositing a mixture of metal film materials oxides on a substrate to form a resistive element, the mixture of metal film materials oxides selected to provide for desired negative temperature coefficient of resistance properties while maintaining the standardized package size.

